

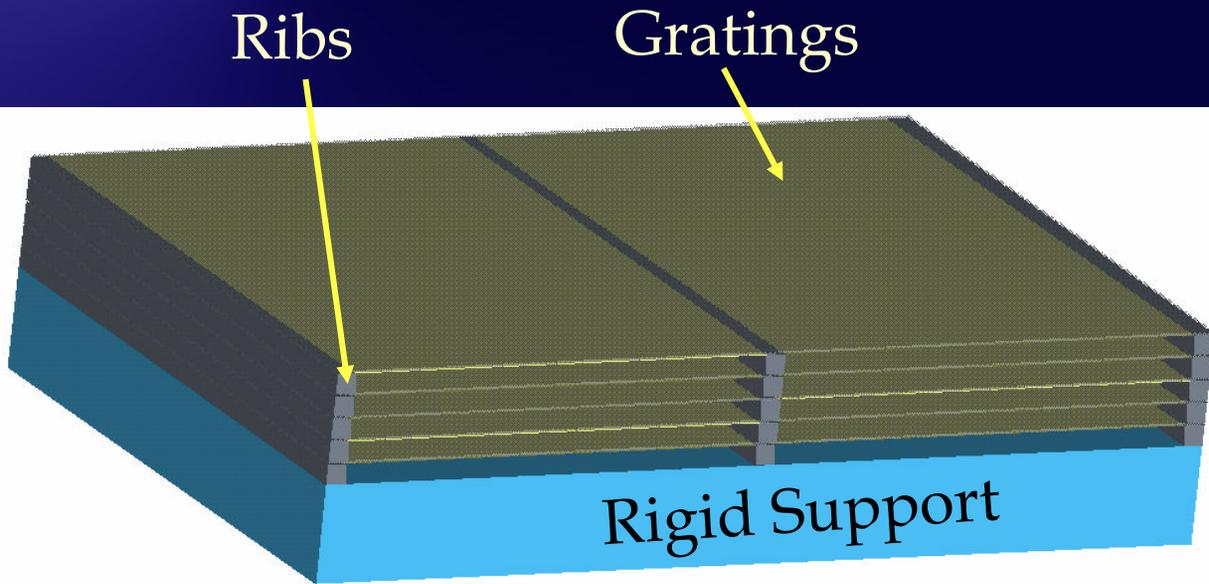
Grating Assembly

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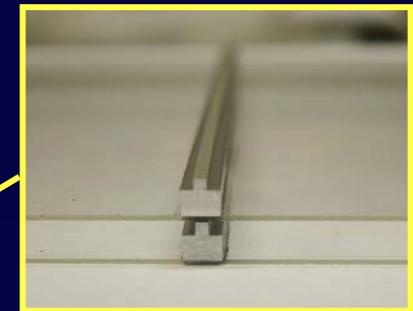
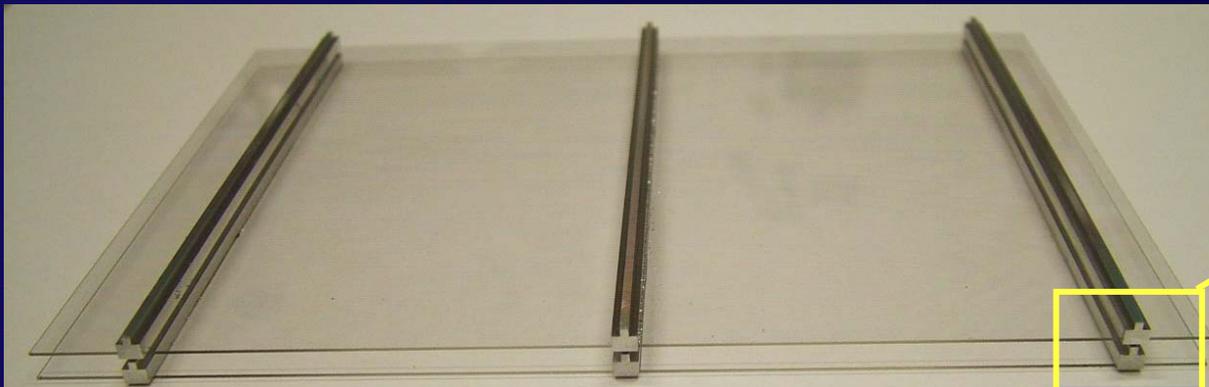
Grating Module Concept



Minimal mass

Rigid module with high resonant frequency

Valid for in-plane & off-plane gratings



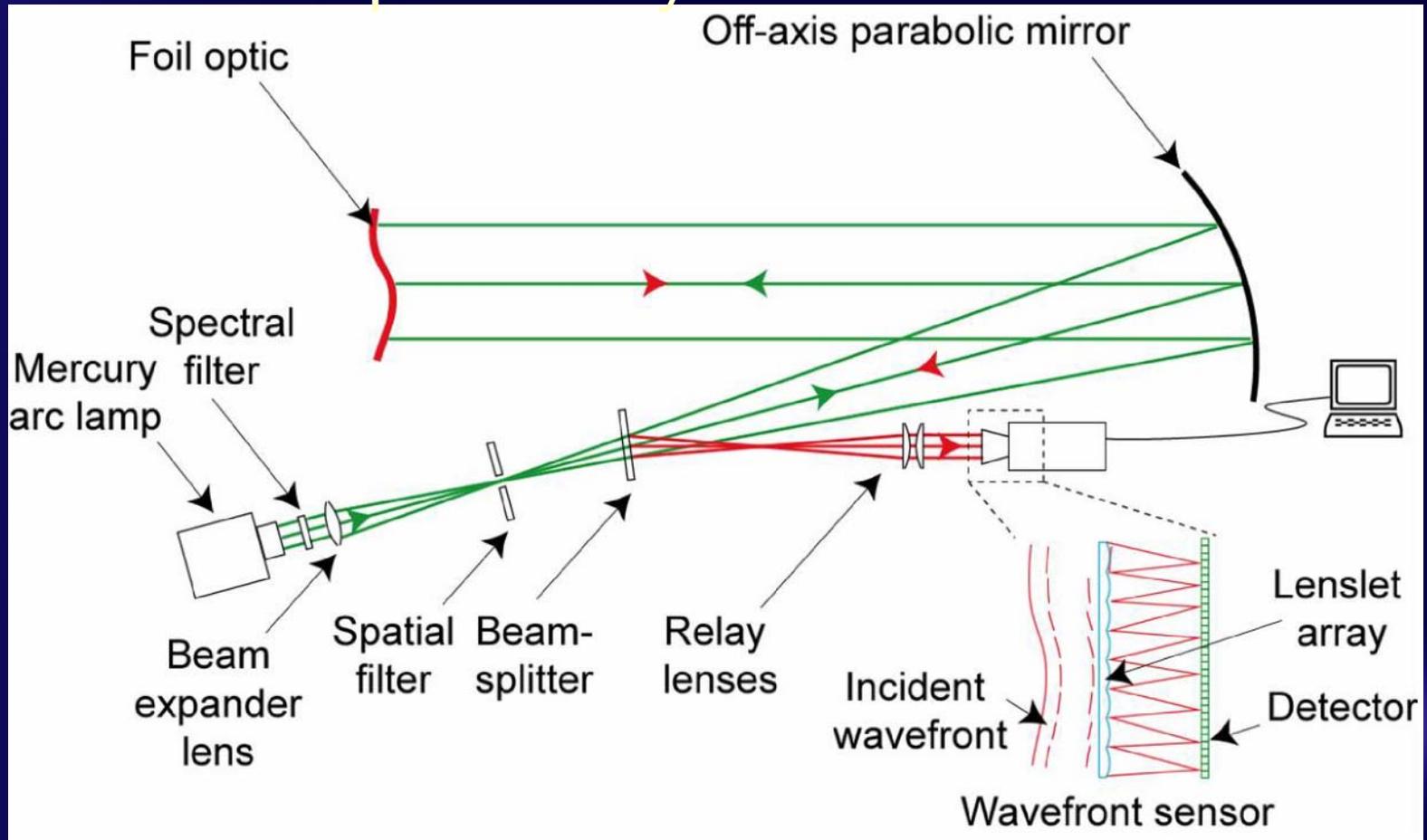
Overview

- ↪ Metrology
 - ↪ Shack-Hartmann metrology tool
 - ↪ Thin optic constraint
- ↪ Improving grating substrate flatness
 - ↪ MRF of silicon wafer at QED
- ↪ Assembly
 - ↪ Assembly parts
 - ↪ Assembly steps
 - ↪ Results

Deep-UV Metrology

Shack-Hartmann metrology tool

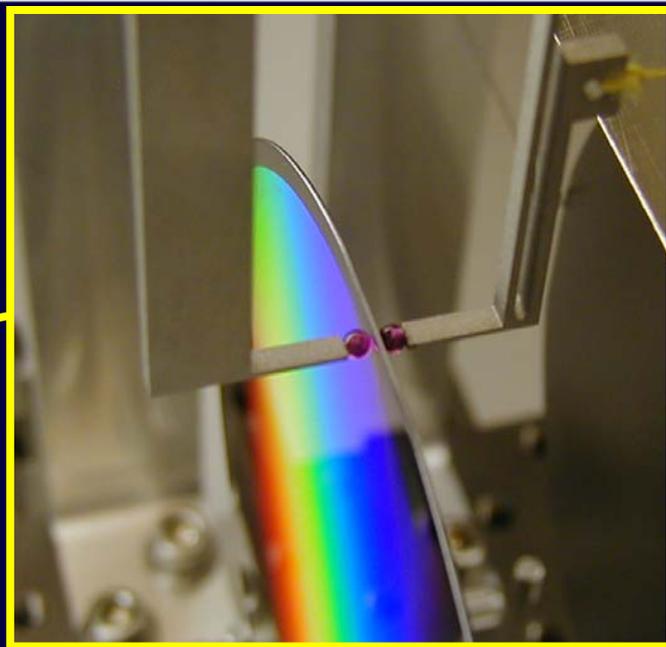
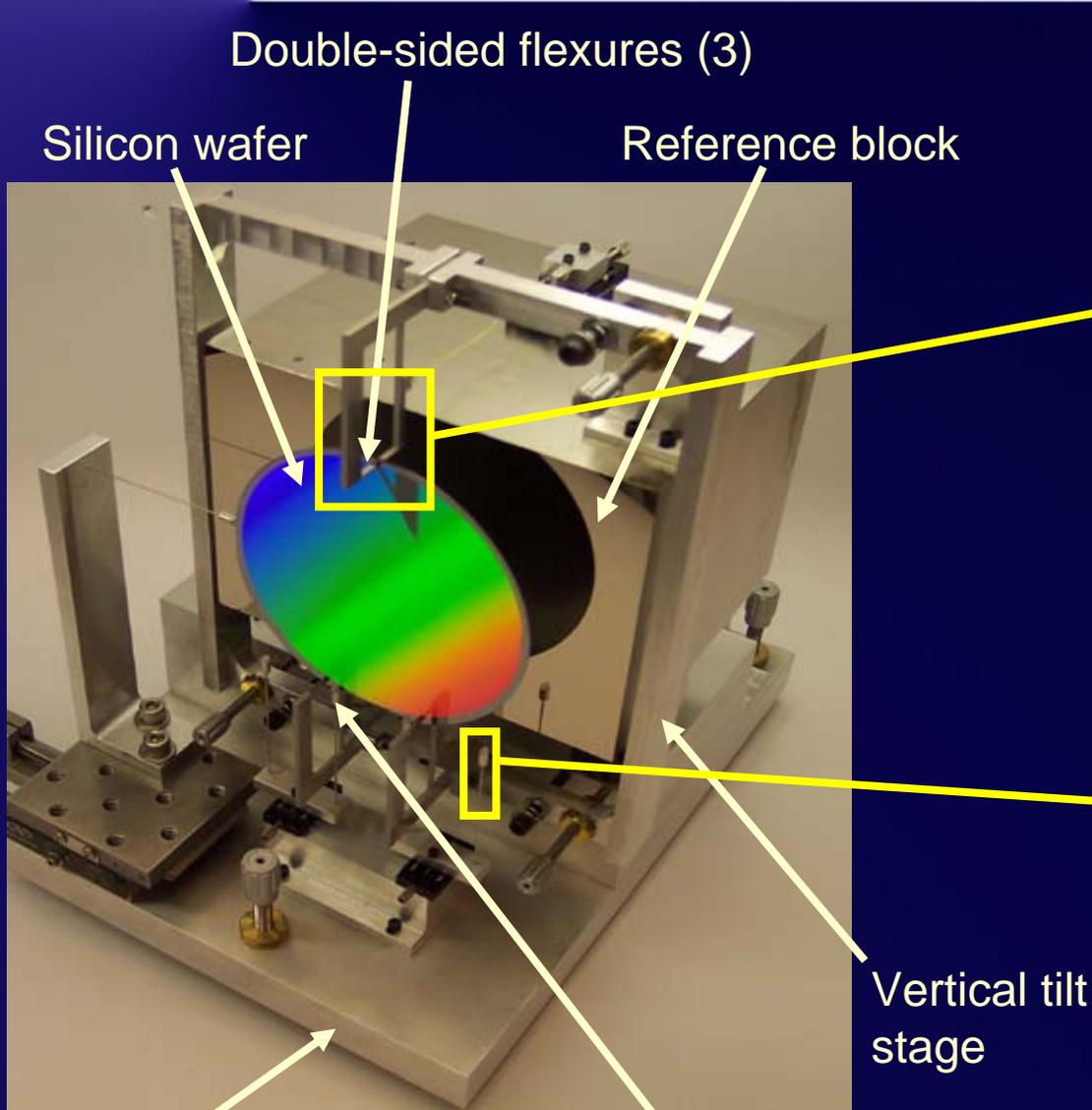
Repeatability ~ 0.4 arcsec



Metrology Challenges with Grating Substrates

- ↪ Gravity Sag (0.4 mm-thick substrates)
- ↪ Friction at mounting points
- ↪ Thermal expansion mismatch between optic and constraint

Thin Optic Constraint



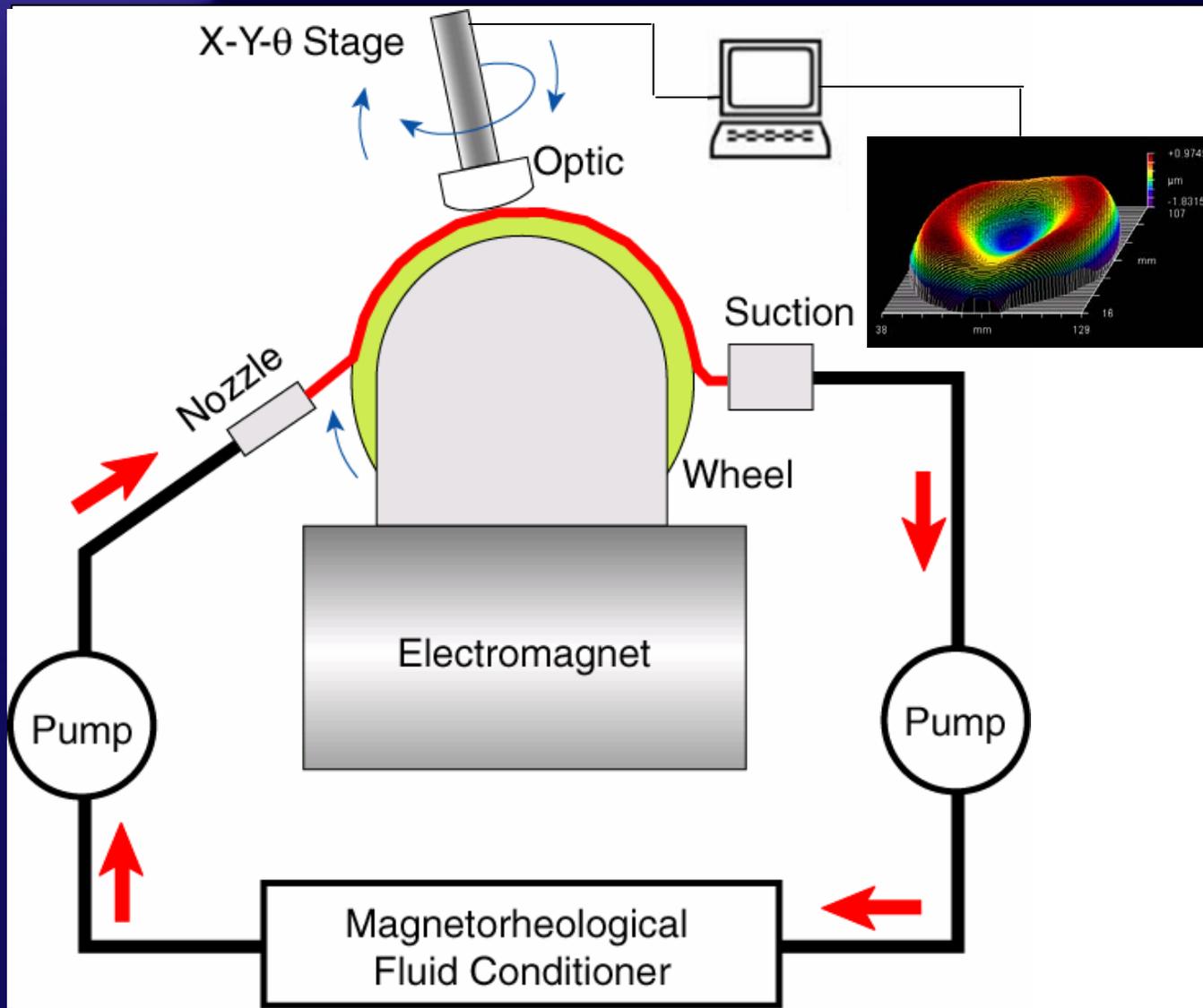
Repeatability

1 arcsec

MIT-Kavli Institute

Horizontal tilt stage
Space Nanotechnology Laboratory

Magneto-Rheological Finishing



QED
Technologies
Rochester, NY

MRF Results

Wafer A

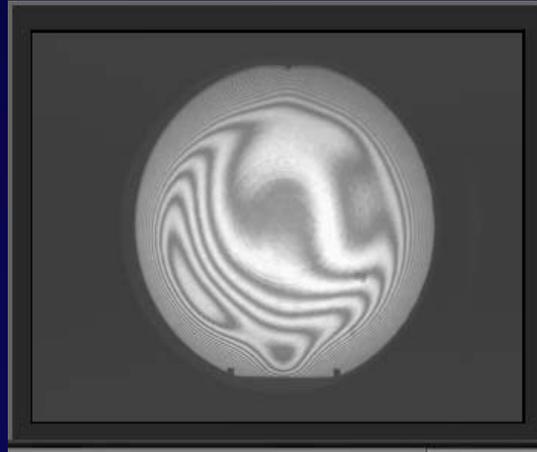
Wafer B

Before MRF

P-V $3.14 \mu\text{m}$

RMS $0.40 \mu\text{m}$

RMS 35 arcsec

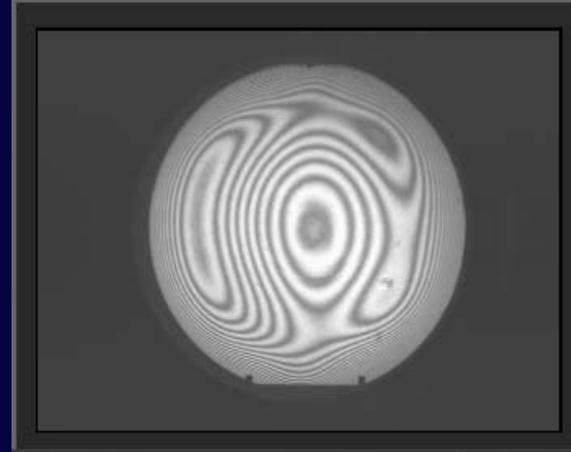


Before MRF

P-V $2.81 \mu\text{m}$

RMS $0.56 \mu\text{m}$

RMS 20 arcsec

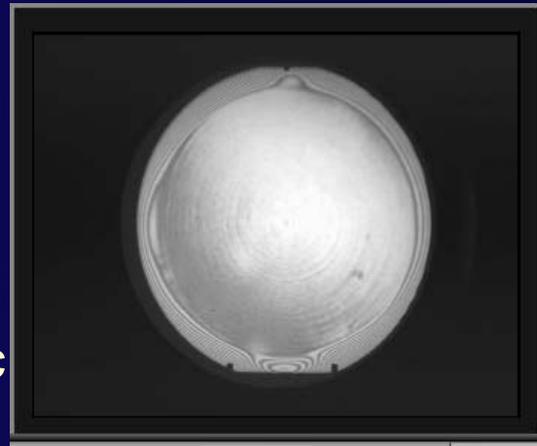


After MRF

P-V $0.18 \mu\text{m}$

RMS $0.02 \mu\text{m}$

RMS 2.5 arcsec

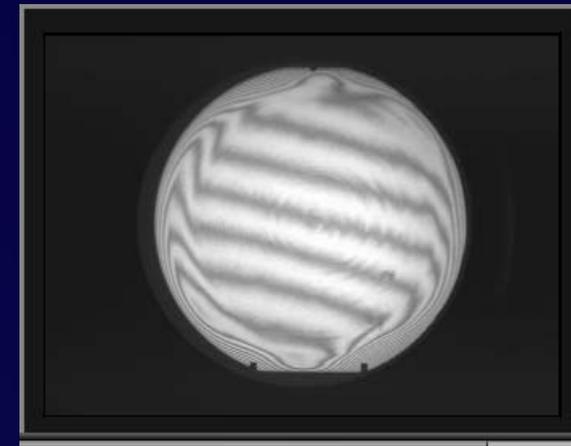


After MRF

P-V $0.07 \mu\text{m}$

RMS $0.01 \mu\text{m}$

RMS 4 arcsec

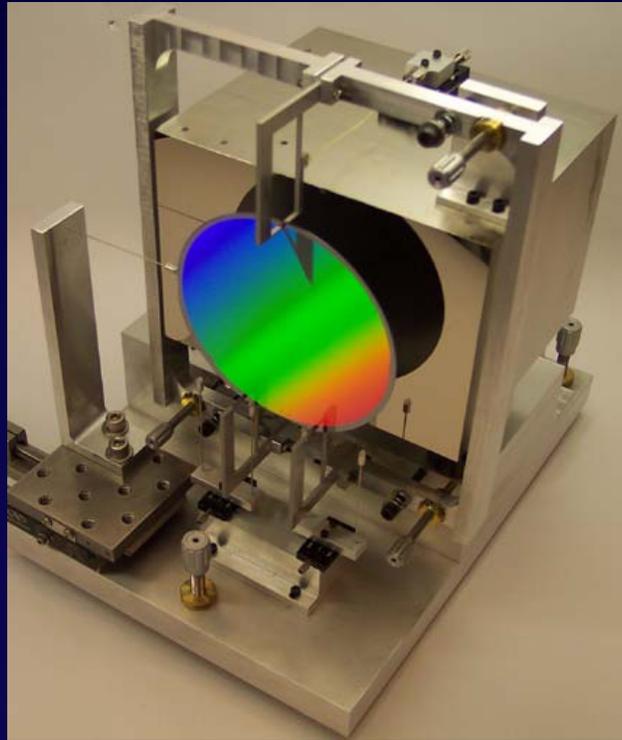


Aperture 81 mm

Aperture 75 mm

Assembly Parts

Thin Optic
Constraint



Vacuum Chuck

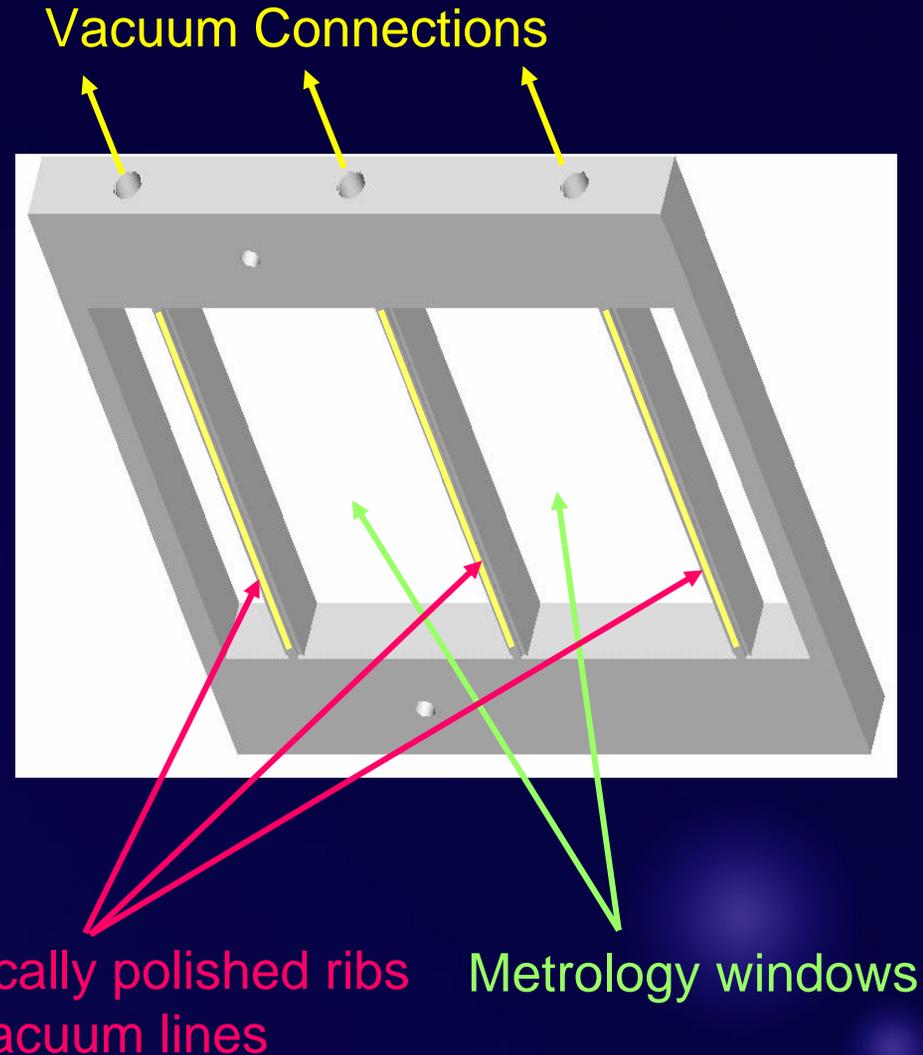
Support Structure
with ribs



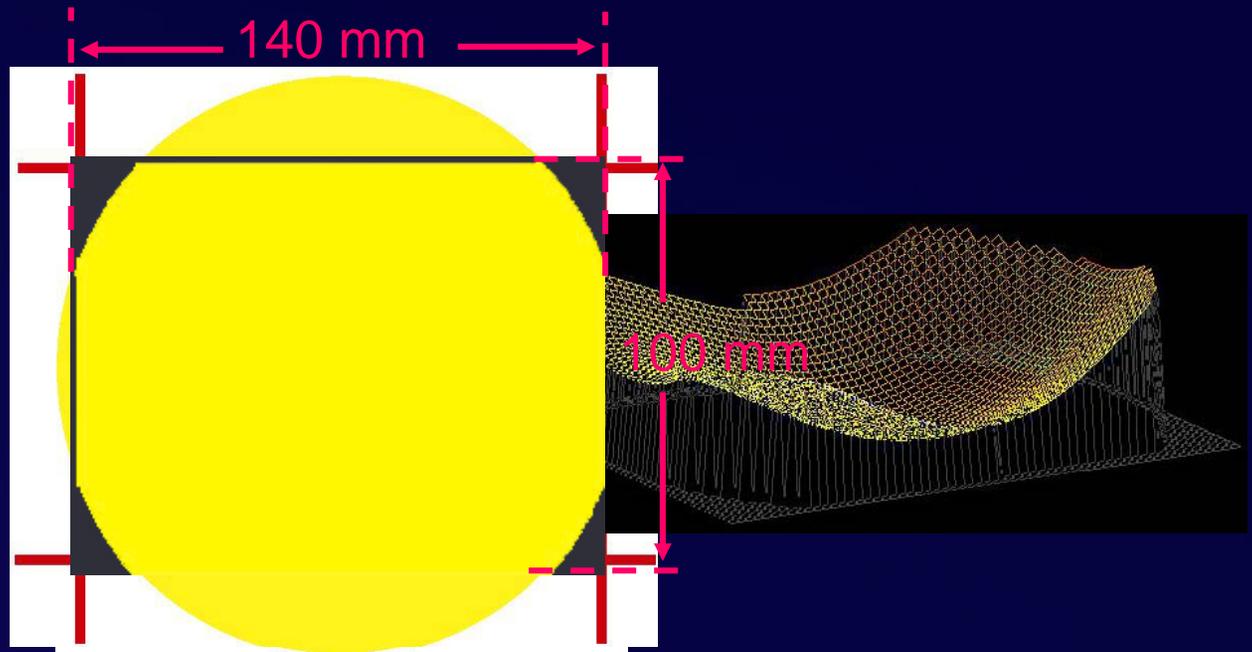
Vacuum Chuck

Functional Requirements

- ↻ Improve overall flatness of grating surface
- ↻ Allow for metrology of grating surface during assembly
- ↻ Allow for rigid constraint during grating maneuvering during assembly

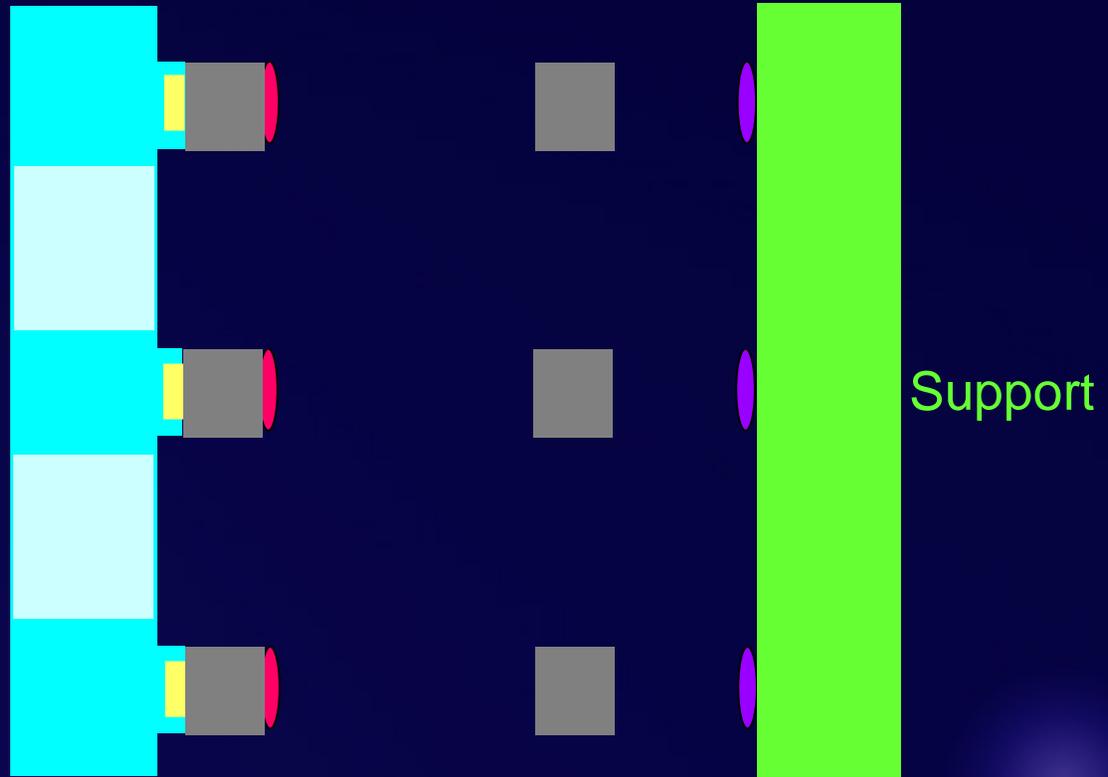


Assembly Steps



Assembly Steps

Vacuum Chuck



Vacuum



Ribs



Grating

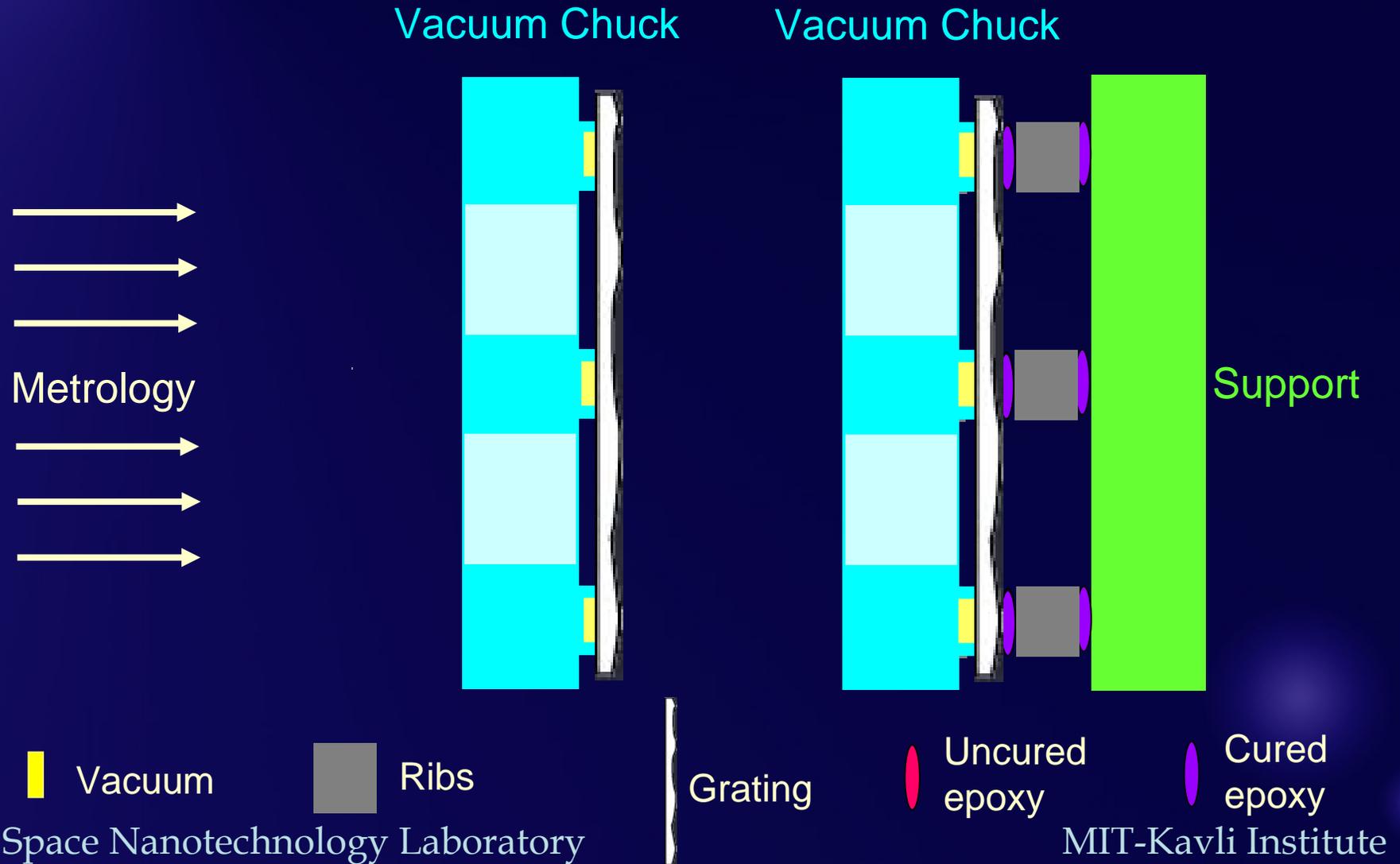


Uncured epoxy



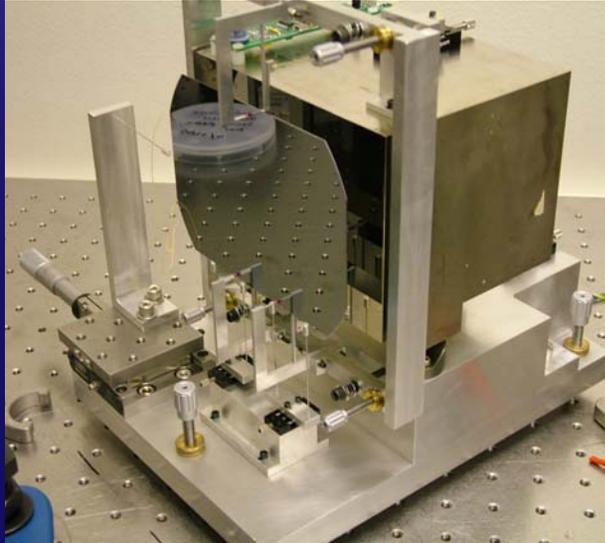
Cured epoxy

Assembly Steps

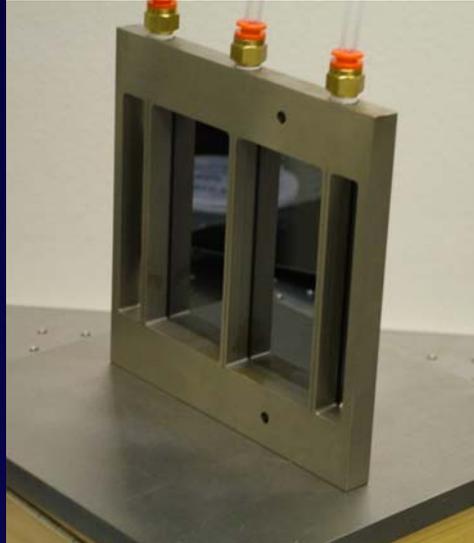


Assembly Hardware

Metrology



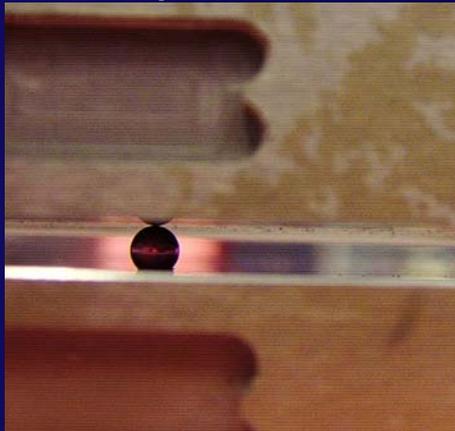
Vacuum Chuck Constraint



Epoxy Curing



Gap Control



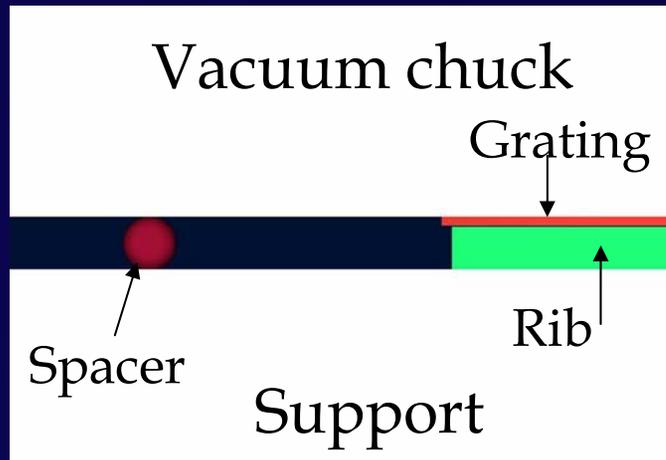
Vacuum chuck

Grating

Spacer

Rib

Support

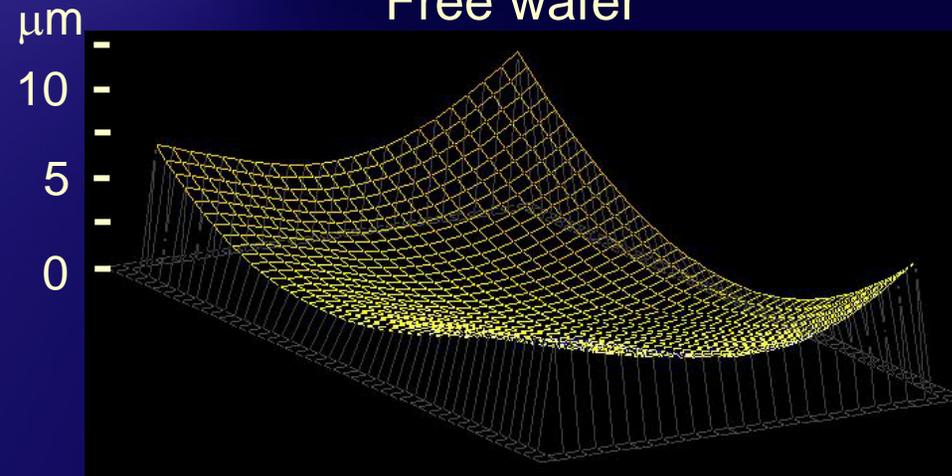


Assembled Grating



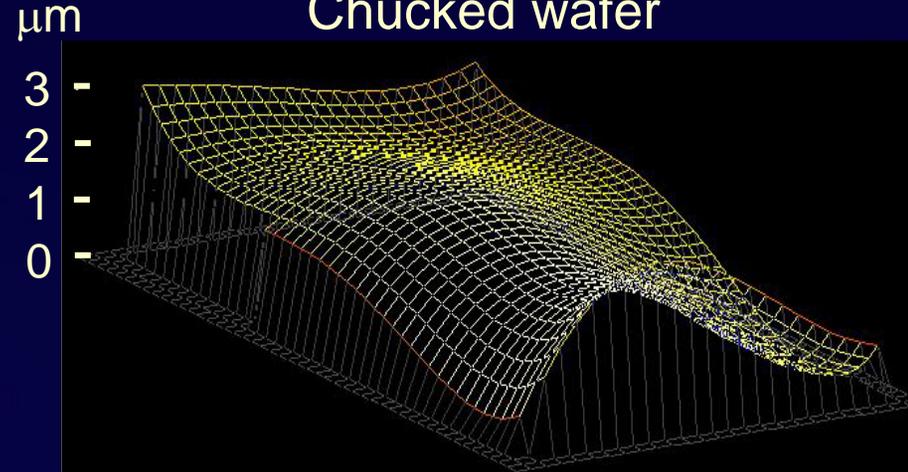
Results

Free wafer



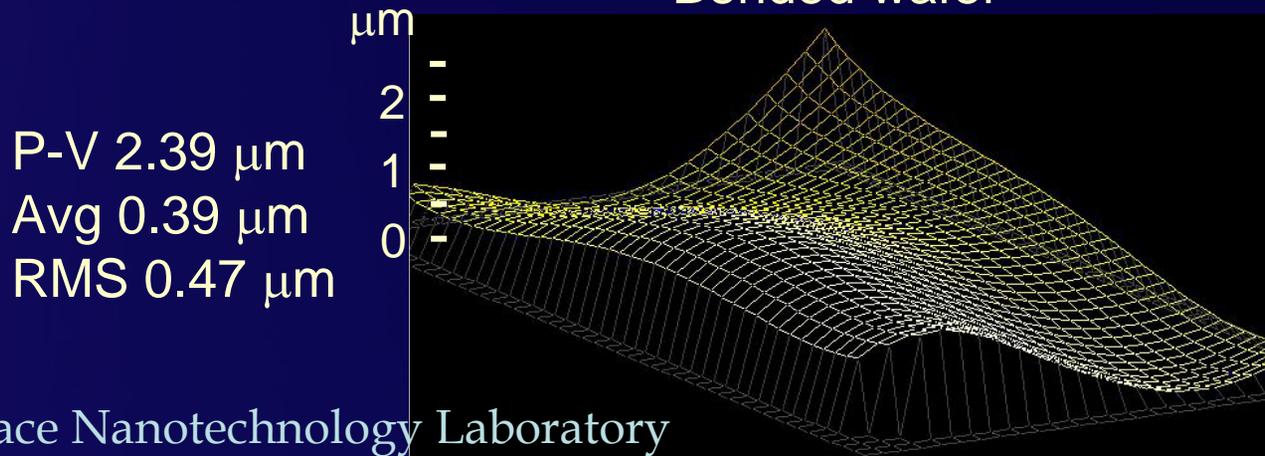
P-V $9.39 \mu\text{m}$
Avg $-3.29 \mu\text{m}$
RMS $1.68 \mu\text{m}$

Chucked wafer



P-V $3.11 \mu\text{m}$
Avg $0.38 \mu\text{m}$
RMS $0.59 \mu\text{m}$

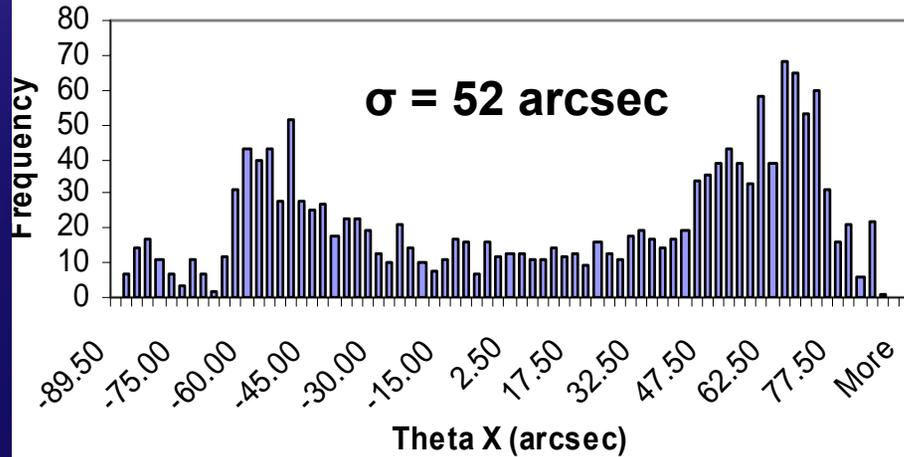
Bonded wafer



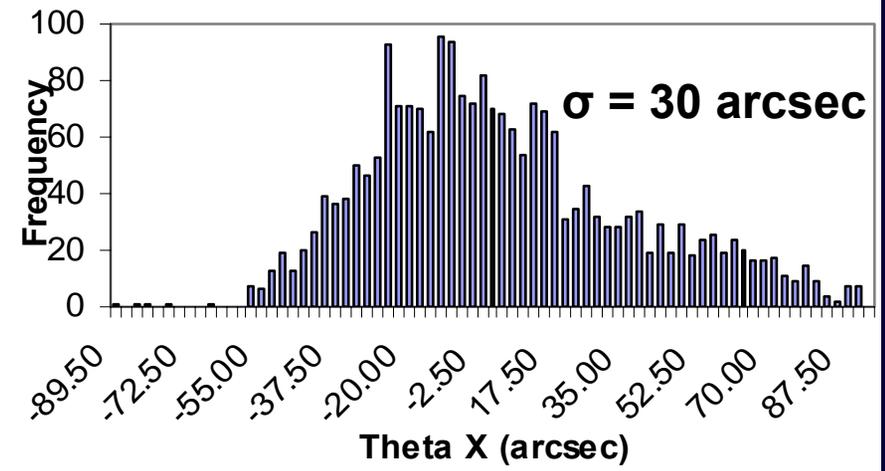
P-V $2.39 \mu\text{m}$
Avg $0.39 \mu\text{m}$
RMS $0.47 \mu\text{m}$

Angle Histograms

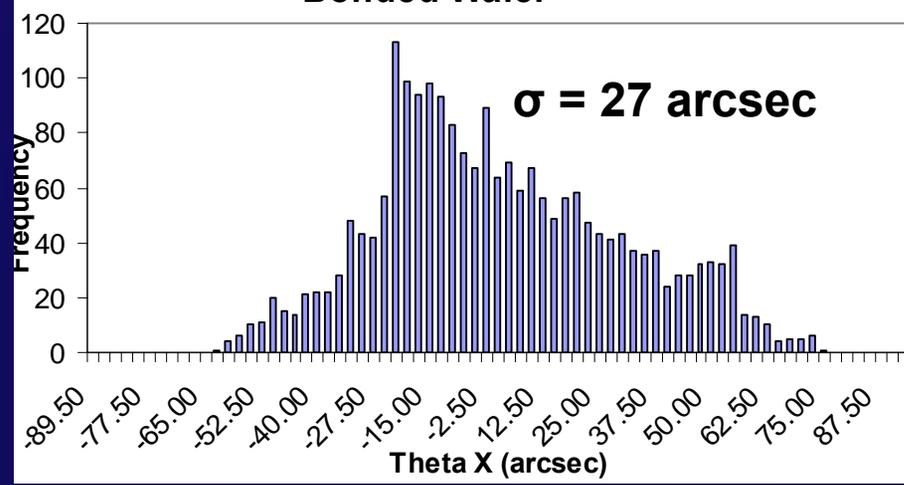
Free Wafer



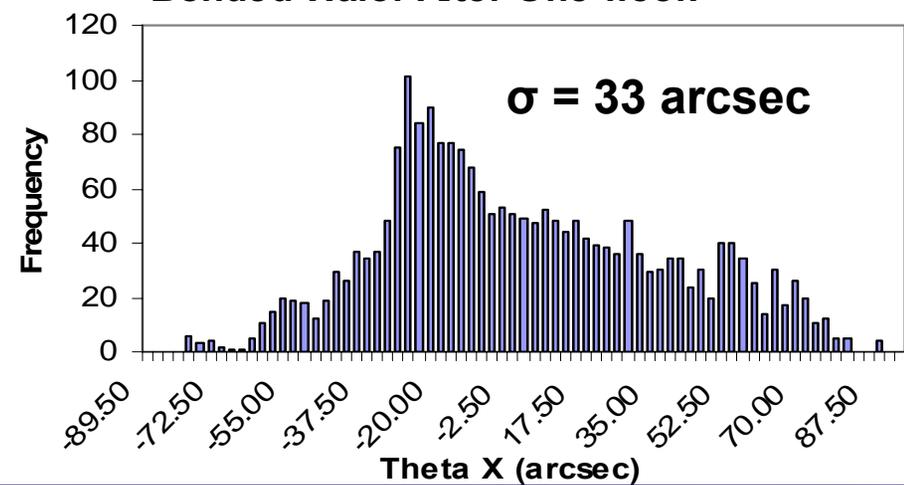
Chucked Wafer



Bonded Wafer



Bonded Wafer After One week



Conclusion

- ✧ Developed a metrology truss with a repeatability of **1 arcsec**
- ✧ Improved silicon wafer surface flatness to **2.5 arcsec RMS** using MRF
- ✧ Developed assembly scheme that loosens tolerance on free-grating flatness (Improved flatness by **~ 20 arcsec**)
- ✧ Ready to go into assembly of multiple levels of gratings



Assembly Steps Back up

